- Designed for Complementary Use with BDW74, BDW74A, BDW74B, BDW74C and BDW74D
- 80 W at 25°C Case Temperature
- 8 A Continuous Collector Current
- Minimum h_{FE} of 750 at 3 V, 3 A

TO-220 PACKAGE (TOP VIEW) B 1 C 3

Pin 2 is in electrical contact with the mounting base.

MDTRACA

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT	
	BDW73		45	
Collector-base voltage (I _E = 0)	BDW73A		60	
	BDW73B	V _{CBO}	80	V
	BDW73C		100	
	BDW73D	-	120	
Collector-emitter voltage (I _B = 0) (see Note 1)	BDW73		45	
	BDW73A	-17	60	
	BDW73B	V _{CEO}	80	V
	BDW73C		100	
	BDW73D		120	
Emitter-base voltage		V _{EBO}	5	V
Continuous collector current		I _C	8	Α
Continuous base current		I _B	0.3	Α
Continuous device dissipation at (or below) 25°C case temperature (see Note 2)	P _{tot}	80	W	
Continuous device dissipation at (or below) 25°C free air temperature (see Note 3	P _{tot}	2	W	
Unclamped inductive load energy (see Note 4)	½LI _C ²	75	mJ	
Operating junction temperature range	T _j	-65 to +150	°C	
Operating temperature range		T _{stg}	-65 to +150	°C
Operating free-air temperature range	T _A	-65 to +150	°C	

NOTES: 1. These values apply when the base-emitter diode is open circuited.

- 2. Derate linearly to 150°C case temperature at the rate of 0.64 W/°C.
- 3. Derate linearly to 150°C free air temperature at the rate of 16 mW/°C.
- 4. This rating is based on the capability of the transistor to operate safely in a circuit of: L = 20 mH, $I_{B(on)}$ = 5 mA, R_{BE} = 100 Ω , $V_{BE(off)}$ = 0, R_S = 0.1 Ω , V_{CC} = 20 V.



BDW73, BDW73A, BDW73B, BDW73C, BDW73D NPN SILICON POWER DARLINGTONS

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electrical characteristics at 25°C case temperature (unless otherwise noted)

	PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
V _{(BR)CEO}	Collector-emitter breakdown voltage	I _C = 30 mA	I _B = 0	(see Note 5)	BDW73 BDW73A BDW73B BDW73C	45 60 80 100			V
					BDW73D	120			
	Collector-emitter	V _{CE} = 30 V	$I_B = 0$		BDW73			0.5	
		$V_{CE} = 30 V$	$I_B = 0$		BDW73A			0.5	
I _{CEO}		$V_{CE} = 40 V$	$I_B = 0$		BDW73B			0.5	mA
	out on ourrone	$V_{CE} = 50 \text{ V}$	$I_B = 0$		BDW73C			0.5	
		$V_{CE} = 60 \text{ V}$	$I_B = 0$		BDW73D			0.5	
		V _{CB} = 45 V	$I_E = 0$		BDW73			0.2	
		$V_{CB} = 60 \text{ V}$	$I_E = 0$		BDW73A			0.2	
		$V_{CB} = 80 \text{ V}$	$I_E = 0$		BDW73B			0.2	
	Collector cut-off current	V _{CB} = 100 V	$I_E = 0$		BDW73C			0.2	
I _{CBO}		V _{CB} = 120 V	$I_E = 0$		BDW73D			0.2	mA
СВО		$V_{CB} = 45 \text{ V}$	$I_E = 0$	$T_{\rm C} = 150^{\circ}{\rm C}$	BDW73			5	
		~-	$I_E = 0$	$T_C = 150$ °C	BDW73A			5	
			$I_E = 0$	$T_C = 150$ °C	BDW73B			5	
		~-	$I_E = 0$	$T_C = 150$ °C	BDW73C			5	
		V _{CB} = 120 V	I _E = 0	T _C = 150°C	BDW73D			5	
I _{EBO}	Emitter cut-off current	V _{EB} = 5 V	I _C = 0	2 3	13 C			2	mA
h _{FE}	Forward current transfer ratio	$V_{CE} = 3 V$ $V_{CE} = 3 V$	$I_C = 3 A$ $I_C = 8 A$	(see Notes 5 ar	nd 6)	750 100		20000	
V _{BE(on)}	Base-emitter voltage	V _{CE} = 3 V	I _C = 3 A	(see Notes 5 ar	nd 6)			2.5	V
V _{CE(sat)}	Collector-emitter saturation voltage	$I_B = 12 \text{ mA}$ $I_B = 80 \text{ mA}$	$I_C = 3 A$ $I_C = 8 A$	(see Notes 5 ar	nd 6)			2.5 4	V
V _{EC}	Parallel diode forward voltage	I _E = 8 A	I _B = 0					3.5	V

NOTES: 5. These parameters must be measured using pulse techniques, $t_p = 300 \mu s$, duty cycle $\leq 2\%$.

thermal characteristics

	PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to case thermal resistance			1.56	°C/W
$R_{\theta JA}$	Junction to free air thermal resistance			62.5	°C/W

resistive-load-switching characteristics at 25°C case temperature

	PARAMETER	TEST CONDITIONS †			MIN	TYP	MAX	UNIT
t _{on}	Turn-on time	I _C = 3 A	$I_{B(on)} = 12 \text{ mA}$	$I_{B(off)} = -12 \text{ mA}$		1		μs
t _{off}	Turn-off time	$V_{BE(off)} = -3.5 \text{ V}$	$R_L = 10 \Omega$	$t_p = 20 \ \mu s, \ dc \le 2\%$		5		μs

[†] Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.

PRODUCT INFORMATION

^{6.} These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

TYPICAL CHARACTERISTICS

TYPICAL DC CURRENT GAIN VS COLLECTOR CURRENT TCS130AD Tc = -40°C Tc = 25°C Tc = 100°C Tc = 3 V t_p = 300 μs, duty cycle < 2% 100 I_C - Collector Current - A

Figure 1.

COLLECTOR-EMITTER SATURATION VOLTAGE

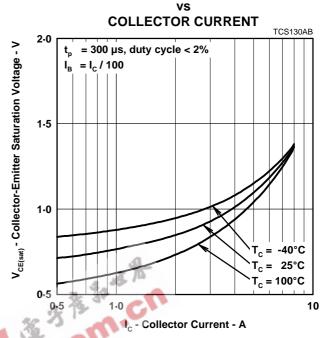
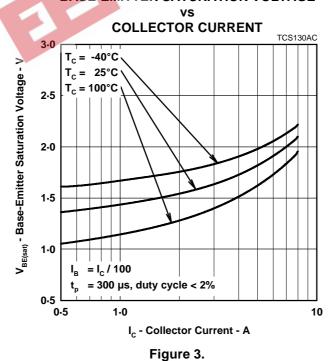


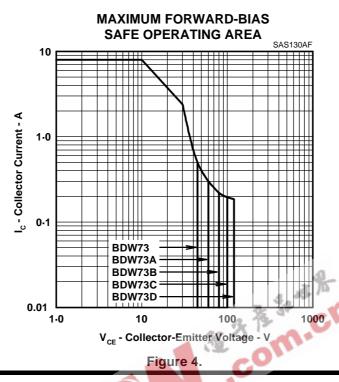
Figure 2.

BASE-EMITTER SATURATION VOLTAGE





MAXIMUM SAFE OPERATING REGIONS



THERMAL INFORMATION

MAXIMUM POWER DISSIPATION VS CASE TEMPERATURE TIS130AA M - under Dissipation VS CASE TEMPERATURE TIS130AA TO DISSIPATION TO DISSIPATION

Figure 5.

PRODUCT INFORMATION

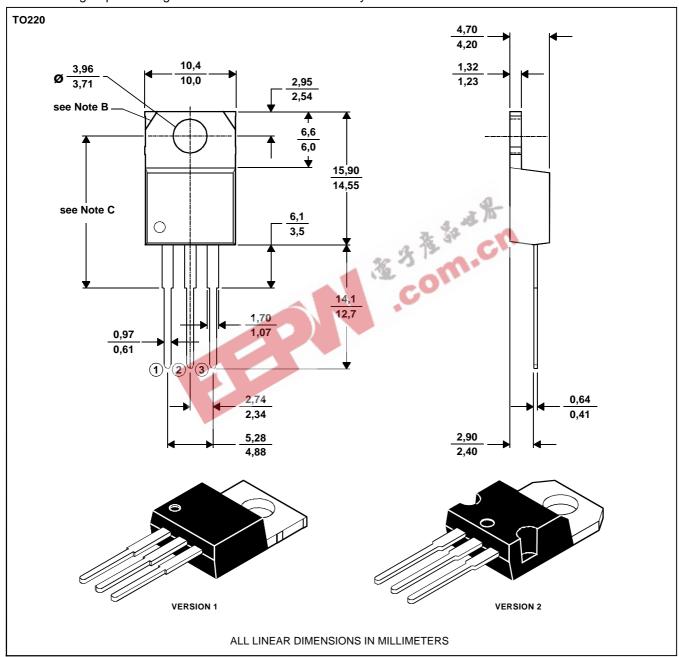
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MECHANICAL DATA

TO-220

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTES: A. The centre pin is in electrical contact with the mounting tab.

B. Mounting tab corner profile according to package version.

C. Typical fixing hole centre stand off height according to package version. Version 1, 18.0 mm. Version 2, 17.6 mm. **MDXXBE**

PRODUCT INFORMATION

BDW73, BDW73A, BDW73B, BDW73C, BDW73D NPN SILICON POWER DARLINGTONS

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